Barry Industries

QFN Flat Lids

LID-XX-XXX*

*See Chart for Specific Part Number

The QFN Lid Series was designed for Barry's C-QFN Air Cavity Family. There are several methods of attachment. Below are some of the more common methods.

QFN Lid Attachment Options:

Epoxy:

Ceramic lid is attached to the top surface of the package wall using B-stage non-conductive epoxy. We recommend our unmetallized lid configuration for this method (LID-XX-0**0**0).

This method does not result in a hermetic seal.

Sealing Glass†:

Ceramic lid is attached to the top surface of the package wall using a low temperature glass.

This method results in a hermetic seal.

Solder:

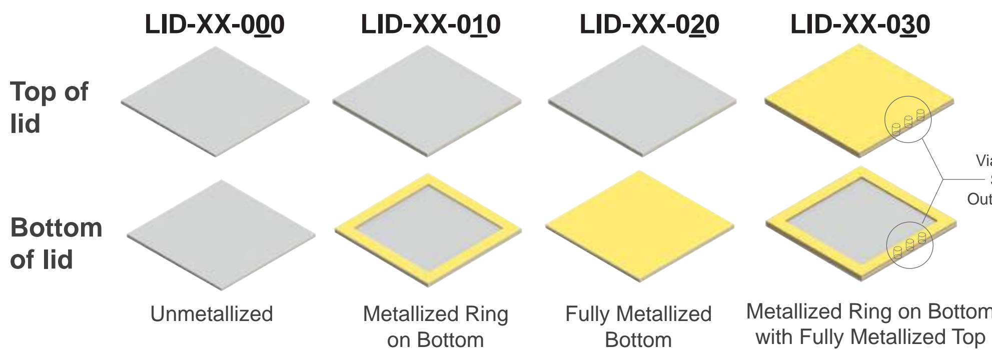
Metallized ceramic lid or metal lid is attached to the metallized top surface of the package wall. The most common alloy used is AuSn eutectic.

This method results in a hermetic seal.

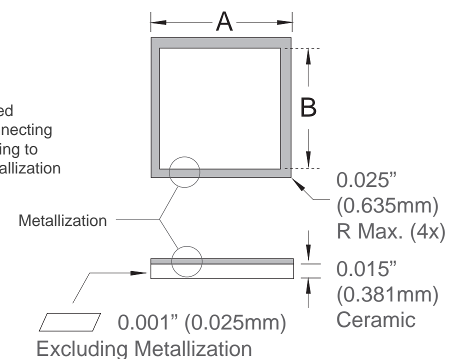
The leak rate of a properly sealed QFN package will be <1x10^-8 atm cc/s He. We provide QFN packages and lids separately in an open configuration. Therefore we test in accordance with MIL-STD-883 method 1014 Test Condition A4 as appropriate for unlidded packages.

† The temperature required to melt even this type of glass may present problems depending on the characteristics of the semiconductor used and the attachment method.

QFN Lid Configurations:



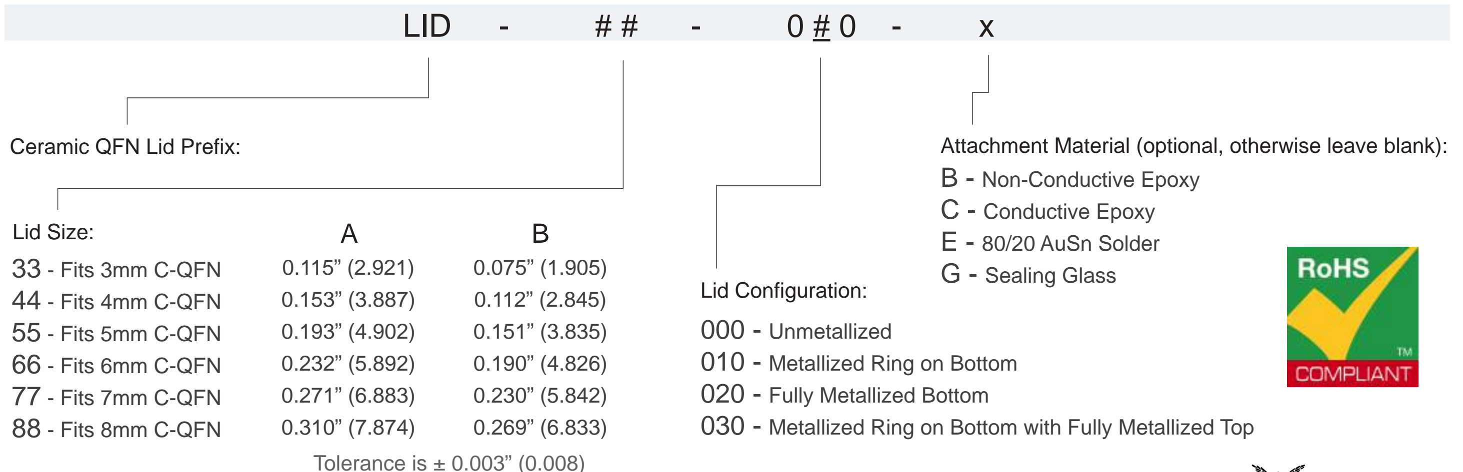
QFN Lid Dimensions:



Metallization: RoHS 50µ inches gold (min.) over 50µ inches nickel (min.) over tungsten or MoMN refractory metallization.

QFN Lid Ordering Information:

Example Part Number: LID-44-030



LID - ## - 0#0 - x

Ceramic QFN Lid Prefix:

Lid Size:

Lid Size	A	B
33 - Fits 3mm C-QFN	0.115" (2.921)	0.075" (1.905)
44 - Fits 4mm C-QFN	0.153" (3.887)	0.112" (2.845)
55 - Fits 5mm C-QFN	0.193" (4.902)	0.151" (3.835)
66 - Fits 6mm C-QFN	0.232" (5.892)	0.190" (4.826)
77 - Fits 7mm C-QFN	0.271" (6.883)	0.230" (5.842)
88 - Fits 8mm C-QFN	0.310" (7.874)	0.269" (6.833)

Tolerance is ± 0.003" (0.008)

Lid Configuration:

- 000 - Unmetallized
- 010 - Metallized Ring on Bottom
- 020 - Fully Metallized Bottom
- 030 - Metallized Ring on Bottom with Fully Metallized Top

Attachment Material (optional, otherwise leave blank):

- B - Non-Conductive Epoxy
- C - Conductive Epoxy
- E - 80/20 AuSn Solder
- G - Sealing Glass

Barry Industries reserves the right to change part number and/or process without notification.

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